

AMENDMENTS TO THE SPECIFICATION

Please amend paragraph [0044] as follows:

[0044] FIG. 5 shows in some detail a side view of a portion of the lower polish head assembly 144. The polish pad 148 is atop the platen 166 that, in turn, is atop the slurry manifold 174 and the polish bell 180. Conduits [172] 170 in the manifold 174 are also shown. An end point probe 190 is shown extending through the polish bell 180, the manifold 174, and into the platen 166. A light pin 192 is shown affixed to the platen 166 by a retaining screw 194, although the pin could alternatively be press fit into the platen. The light pin 192 is of a plastic, epoxy, or urethane material and extends through the platen, through holes 182 as shown in FIG. 4 and also through the polishing pad 148 when the pad is in place. Because the light pin initially extends through the polishing pad 148, the pin can be used as a registration guide for providing proper position of the pad 148 on the platen 166. As explained more fully below, the top portion of light pin 192 is subsequently trimmed off flush with the top surface of polishing pad 148. Accordingly the top portion of light pin 192, the portion that is subsequently removed, is shown in phantom in FIG. 5.